

# Microelectronics Adhesives

## DIE ATTACH ADHESIVES

Product #	Volume Resistivity (ohms-cm)	Application Technique	Comments
118-06 (PP)	0.0002	Pad print	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (SP)	0.0002	Screen print	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (SD)	0.0002	Syringe Dispense	Ionically clean, microelectronic and die attach conductive adhesive.
118-06 (ST)	0.0002	Stencil	Ionically clean, microelectronic and die attach conductive adhesive.
122-38 (SD)	0.0002	Syringe Dispense	Ionically clean, microelectronic and die attach conductive adhesive. Bonds to tin, lead and gold surfaces.
122-33 (SD)	$1 \times 10^{16}$	Syringe Dispense	Thermally conductive, dielectric adhesive.

## SURFACE MOUNT ADHESIVES

Product #	Conductivity (ohms-cm)	Application Technique	Comments
102-32	0.0001	Syringe Dispense	High temperature resistant. Flexible.
120-25	0.0005	Screen print	Can be rebonded / reworked. Flexible.
106-32A	0.0001	Syringe Dispense	High temperature resistant.
GPC-251 A/B	0.0002 - 0.005	Stencil	Silver filled, two part, room temperature curing epoxy adhesive. Designed for electrical and mechanical attachments of components and devices. Good for hand application.
118-15 A/B	0.0001 - 0.0004	Syringe Dispense	Easy 1 to 1 mix ratio. Low temperature curing. Long pot life.
119-05	0.00015	Syringe Dispense or Stencil	Can remain in liquid state up to 5 days without drying out. Single component.
118-06	0.0008	Pad print	B-stageable, electrically conductive epoxy adhesive.

## FLIP CHIP ADHESIVES

Product #	Conductivity (ohms-cm)	Comments
GPC-251 A/B	0.0002 - 0.005	Silver filled, two part, room temperature curing epoxy adhesive. Designed for electrical and mechanical attachments of components and devices. Good for hand application.
GPC-352-1 A/B-187	0.0005	Silver filled, two part, heat curing epoxy adhesive. Cures with excellent conductivity and is less sensitive to handling and ambient conditions. Typical applications are surface mount, component and heat sink attachment.
GPC-352-1 A/B-944	0.0005	Same as above, except hardener B-944 provides extended pot life.
121-20 A/B	$1 \times 10^{12}$ x,y axis 0.0001 z axis	Anisotropic, silver filled, two component, low temperature curing epoxy adhesive. Applications include conductive splicing of ribbon cables, bonding of flex circuits to PC boards, E.L. panels and touch screens and bonding of electrical components where short circuits caused by closely spaced contact pads are a concern.
121-23	$1 \times 10^{12}$ x,y axis 0.001 z axis	Anisotropic, conductive, screen-printable, B-stageable epoxy adhesive suitable for application by screen-printing, dipping and syringe dispensing. Applications include bonding of flex circuits to PC boards and electrical attachment of surface mounted devices. Excellent adhesion to a variety of metallic contact pad compositions.

## FLIP CHIP UNDERFILL MATERIALS

Product #	Volume Resistivity (ohms-cm)	Comments
120-27A/B-187	$1 \times 10^{15}$	Black, low viscosity, two component, underfill epoxy potting and encapsulating compound. Formulated to rapidly release entrapped air during cure, providing a pin hole free surface.
113-33A/B187	$1 \times 10^{15}$	Black, sag resistant glob top, flame-out, two component, epoxy potting and encapsulating compound. Material is crack resistant with a working life greater than four hours.
102-11A/B-187	$1 \times 10^{15}$	Black, crack resistant, flameout epoxy compound. Features long pot life and excellent resistance to thermal shock. Popular applications are encapsulating and bonding.
102-12A/B-187	$1 \times 10^{15}$	Black, thermal cycle resistant, epoxy compound with excellent resistance to thermal shock. Requires mild heat cure and has working life of greater than four hours.
116-04A/B-187	$1 \times 10^{15}$	Black, low viscosity, two component, underfill epoxy potting and encapsulating compound. Formulated for applications requiring excellent thermal conductivity.

PLEASE CONTACT US FOR OTHER MARKET SPECIFIC PRODUCT SELECTOR GUIDES



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Our in-depth experience with conductive filler technology, particle size and shape allows us to fine tune the performance, as well as the application process and cure cycle to best meet our customers' production requirements.

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